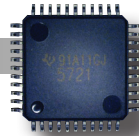


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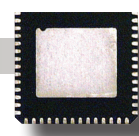


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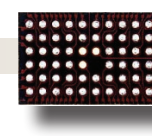
## QFP

Pin count: 32 to 208 pins  
 Body size: 5 x 5 mm to 28 x 28 mm  
 Pitch: 0.4 mm, 0.5 mm, 0.65 mm  
 Height: QFP = 2.7 mm to 4.1 mm  
 LQFP = 1.4 mm  
 TQFP = 1.0 mm



## QFN/SON

Pin count: 6 to 64 pins  
 Body size: 1.5 x 1.5 mm to 9 x 9 mm  
 Pitch: 0.4 mm, 0.5 mm, 0.65 mm  
 Height: VQFN/VSON = 0.9 mm  
 WQFN/WSON = 0.75 mm  
 UQFN/USON = 0.55 mm  
 X2QFN = 0.37 mm



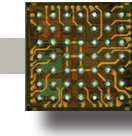
## FBGA/CSP

Pin count: 6 to 361 pins  
 Body size: 1.5 x 1.5 mm to 16 x 16 mm  
 Pitch: 0.4 mm, 0.5 mm, 0.65 mm, 0.8 mm  
 Height: MicroStar BGA™, MicroStar Junior, nFBGA = 1.0 mm to 1.5 mm  
 Microstar WT = 0.8 mm  
 Microstar ZT = 0.61 mm  
 Microstar UT = 0.55 mm  
 Microstar CSP = 0.4 mm



## PBGA

Pin count: 252 to 672 pins  
 Body size: 17 x 17 mm to 35 x 35 mm  
 Pitch: 1.0 mm, 1.27 mm  
 Height: PBGA = 1.38 mm to 3.2 mm



## WCSP

Pin count: 2 to 81 pins  
 Body size: 0.8 x 1.2 mm to 4 x 4 mm  
 Pitch: 0.3 mm, 0.4 mm, 0.5 mm  
 Height: PicoStar™ = 0.152 mm  
 WCSP = 0.4 mm to 0.625 mm

## TO



### TO-220

Pin count: 3 pins  
 Body Length: 9.65-10.67 mm  
 Body Width: 8.38-9.02 mm  
 Lead Width: 0.71-0.89 mm  
 Package Width: 26.92-31.24 mm  
 Pitch: 2.54 mm  
 Height: 4.7 mm

## 3-pin



### LP

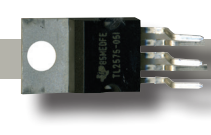
Pin count: 3 pins  
 Body Length: 4.44-5.21 mm  
 Body Width: 4.32-5.34 mm  
 Lead Width: 0.41-0.56 mm  
 Package Width: 4.44-5.212 mm  
 Pitch: 1.27 mm  
 Height: 5.34 mm

## 5-pin



### PFM/TO-263/DDPAK

Pin count: 3 pins  
 Body Length: 9.65-10.67 mm  
 Body Width: 8.38-9.65 mm  
 Lead Width: 0.66-0.91 mm  
 Package Width: 14.6-15.88 mm  
 Pitch: 2.54 mm  
 Height: 4.83 mm



### PFM

Pin count: 5 pins  
 Body Length: 9.65-10.67 mm  
 Body Width: 8.38-9.25 mm  
 Lead Width: 0.75-1.02 mm  
 Package Width: 24.64-25.15 mm  
 Pitch: 1.7 mm  
 Height: 4.7 mm

## PDIP



### PDIP

Pin count: 8-24 pins  
 Body Length: 9.02-32 mm  
 Body Width: 6.10-7.11 mm  
 Lead Width: 0.38-0.53 mm  
 Package Width: 8.26-9.02 mm  
 Pitch: .51-2.54 mm  
 Height: 5.08 mm

## SOIC



### SOIC

Pin count: 8-28 pins  
 Body Length: 4.8-18.03 mm  
 Body Width: 3.81-7.6 mm  
 Lead Width: 0.35-0.51 mm  
 Package Width: 5.8-10.63 mm  
 Pitch: 1.27 mm  
 Height: 1.75-2.65 mm

## SOP



### SOP

Pin count: 8-24 pins  
 Body Length: 5.6-15.3 mm  
 Body Width: 5-5.6 mm  
 Lead Width: 0.35-0.51 mm  
 Package Width: 7.4-8.2 mm  
 Pitch: 1.27 mm  
 Height: 2 mm

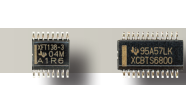
## SSOP



### SSOP

Pin count: 8-56 pins  
 Body Length: 2.75-18.54 mm  
 Body Width: 2.7-7.59 mm  
 Lead Width: 0.15-0.34 mm  
 Package Width: 3.75-10.67 mm  
 Pitch: 0.64-0.65 mm  
 Height: 1.3-2.79 mm

## QSOP



### QSOP

Pin count: 16-24 pins  
 Body Length: 4.8-8.74 mm  
 Body Width: 3.81-3.99 mm  
 Lead Width: 0.2-0.3 mm  
 Package Width: 5.8-6.2 mm  
 Pitch: 0.64 mm  
 Height: 1.75 mm

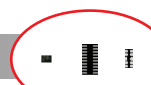
## TSSOP



### TSSOP

Pin count: 8-80 pins  
 Body Length: 2.9-17.1 mm  
 Body Width: 4.3-6.2 mm  
 Lead Width: 0.19-0.23 mm  
 Package Width: 6.2-8.3 mm  
 Pitch: 0.4-0.65 mm  
 Height: 1.2 mm

## μSON



### μSON

Pin count: 6-20 pins  
 Body Length: 1.4-4.05 mm  
 Body Width: 0.95-2.05 mm  
 Lead Width: 0.15-0.25 mm  
 Package Width: 0.95-2.05 mm  
 Pitch: 0.4-0.5 mm  
 Height: 0.55-0.6 mm

## VSSOP



### VSSOP

Pin count: 8-10 pins  
 Body Length: 1.9-3.10 mm  
 Body Width: 2.2-3.10 mm  
 Lead Width: 0.17-0.27 mm  
 Package Width: 3-5.05 mm  
 Pitch: 0.23-0.5 mm  
 Height: 0.9-1.10 mm

## TVSSOP



### TVSSOP

Pin count: 14-56 pins  
 Body Length: 3.5-11.4 mm  
 Body Width: 4.3-4.5 mm  
 Lead Width: 0.13-0.23 mm  
 Package Width: 6.2-6.6 mm  
 Pitch: 0.4 mm  
 Height: 1.2 mm

## SOT



### SOT

Pin count: 3-8 pins  
 Body Length: 0.95-3 mm  
 Body Width: 0.75-1.75 mm  
 Lead Width: 0.10-0.38 mm  
 Package Width: 0.95-3 mm  
 Pitch: 0.35-0.65 mm  
 Height: 0.50-1.45 mm

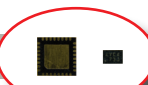
## PicoStar



### PicoStar™

Pin count: 6 pins  
 Body Length: 1.16-1.85 mm  
 Body Width: 0.76-1.45 mm  
 Lead Width: 0.18-0.22 mm  
 Package Width: 0.76-1.45 mm  
 Pitch: 0.40 mm  
 Height: 0.15 mm

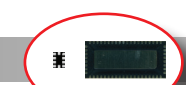
## μQFN



### μQFN

Pin count: 8-32 pins  
 Body Length: 1.45-5.15 mm  
 Body Width: 1.45-5.15 mm  
 Lead Width: 0.2-0.3 mm  
 Package Width: 1.45-5.15 mm  
 Pitch: 0.5 mm  
 Height: 0.5-0.6 mm

## WQFN



### WQFN

Pin count: 10-56 pins  
 Body Length: 1.95-11.15 mm  
 Body Width: 1.45-5.15 mm  
 Lead Width: 0.20-0.3 mm  
 Package Width: 1.45-5.15 mm  
 Pitch: 0.5 mm  
 Height: 0.8 mm

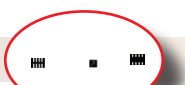
## WCSP



### WCSP

Pin count: 4-81 pins  
 Body Length: 0.74-3.79 mm  
 Body Width: 0.74-3.69 mm  
 Lead Width: 0.21-0.30 mm  
 Package Width: 0.74-3.69 mm  
 Pitch: 0.4 mm  
 Height: 0.4-0.63 mm

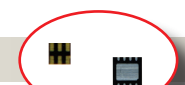
## X2SON



### X2SON

Pin count: 6-8 pins  
 Body Length: 0.95-2.05 mm  
 Body Width: 0.95-1.45 mm  
 Lead Width: 0.14-0.25 mm  
 Package Width: 0.95-1.45 mm  
 Pitch: 0.35-0.50 mm  
 Height: 0.4 mm

## WSON



### WSON

Pin count: 6-16 pins  
 Body Length: 1.90-3.40 mm  
 Body Width: 1.90-1.45 mm  
 Lead Width: 0.25-0.25 mm  
 Package Width: 1.45-1.90 mm  
 Pitch: 0.40-0.50 mm  
 Height: 0.8 mm

## XLGA



### XLGA

Pin count: 4-81 pins  
 Body Length: .77 mm  
 Body Width: .77 mm  
 Lead Width: .18-.22 mm  
 Package Width: .13-.145 mm  
 Pitch: .4-.5 mm  
 Height: .144-.15 mm

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